

NOTE:

1. MATERIAL:

- 1.1 INSULATOR:LCP+30%GF, UL94 V-0.
- 1.2 CONTACT 1~4PIN: C5191-EH.
- 1.3 CONTACT 5~9PIN: C5191-EH.
- 1.4 SHELL: SUS304 3/4H

2. PLATING:

- 2.1 CONTACT:  
CONTACT AREA: GOLD PLATING.  
SOLDER AREA: 100u" Min MATTE TIN PLATING.  
UNDER PLATE: 50u" Min NICKEL PLATING.
- 2.2 SHELL:50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:

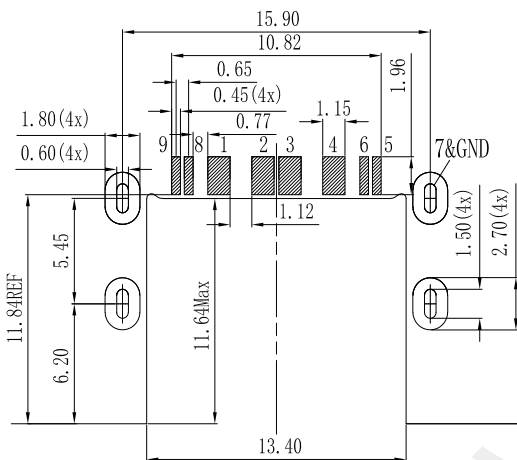
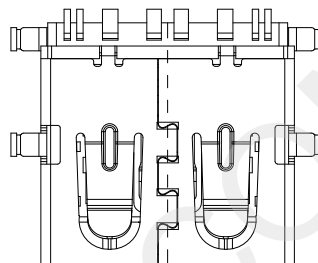
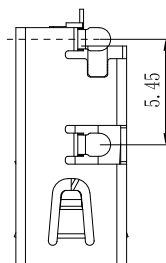
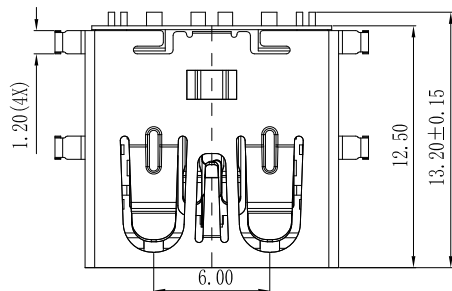
- 3.1 ELECTRICAL CHARACTERISTICS:  
CONTACT RESISTANCE:30mΩ MAXIMUM  
CONTACT CURRENT RATING: 3A  
DIELECTRIC WITHSTANDING VOLTAGE: 500 V R.M.S.  
INSULATION RESISTANCE: 100 MEGOHMS MIN  
OPERATING TEMPERATURE: -25° C ~ +85° C

3.2 MECHANICAL:

- MATING FORCE: 8-25N .
- UNMATING FORCE: 10-25N .
- After lifespan testing: 6N Min.

4. PART MUST COMPLY ROHS SPECIFICATION

- 5. WAVE SOLDER: THE CONNECTOR SHALL BE MOUNTED ON THE PCB. THE TEMPERATURE OF THE SOLDER SHALL BE 260±5° C AND IMMERSION DURATION 5 SECONDS.
- 6. ROHS. HF



TOLERANCE: ±0.05, RECOMMENDED PCB LAYOUT (TOP VIEW)

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

3	SHELL	SUS304-3/4H	50u" Min. NICKEL PLATED OVERALL
2	CONTACT	C5191-EH	GOLD PLATED ON CONTACT AREA
1	HSG	LCP+30%GF	UL94V-0 BLACK
NO.	PART NAME	MATERIAL	DESCRIPTION



深圳市华宇创精密电子有限公司

TOLERANCE: XX ±0.30 XXX ±0.25 XXX ±0.15 X° ±2° X.X° ±0.5°	DRAWN BY :	DATE :	PART NAME:
	陈一鸣	2014-02-23	USB 3.1 AF 10Gbps 沉板 H=3.5mm
UNIT: mm [inch] SCALE:1:1 SIZE: A4	CHECKED BY:	DATE :	PART NO.
	马跃	2014-02-23	HVC184-USBA09-350
	APPROVED BY:	DATE :	DRAW NO.
	邱敏	2014-02-23	HVC-2604281543
			SHEET NO. 1 OF 1